



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20200127000.1
Qualification of new Mold & Mount Compound for Select Devices
Change Notification / Sample Request

Date: February 18, 2020
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services

20200127000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DP83848YB/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200127000.1		PCN Date:	Feb. 18, 2020	
Title:	Qualification of new Mold & Mount Compound for Select Devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	May 18, 2020		Estimated Sample Availability:	Date provided at sample request	
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of a new mount and mold compound for the devices in the Product Affected section below as follows:					
Group 1 device:					
	Current	New			
Mount Compound	1400013111	1400160111			
Mold Compound	18003331G1	180082310F			
Group 2 device:					
	Current	New			
Mount Compound	1400013111	1400153112			
Mold Compound	1800008131	18008231U1			
Reason for Change:					
Continuity of supply. Current mount compound and mold compound material is no longer available.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .		
Changes to product identification resulting from this PCN:					
None					
Product Affected: Group 1					
LM97593VH/NOPB					
Product Affected: Group 2					
DP83848VYB/NOPB		DP83848YB/NOPB		DP83848YBX/NOPB	

Qualification Report

Approve Date 16-Jan-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DP83848YB/NOPB	Qual Device: LM97593VH/NOPB
PC	Preconditioning	Level 3 - 245C	-	3/924/0
PC	Preconditioning	Level 3 - 260C	3/693/0	-
AC	Autoclave, 121C	96 Hours	3/231/0	3/231/0
BHAST	Biased HAST, 110C	264 Hours	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0	3/231/0
TC	Temperature Cycle, - 65C/150C	500 Cycles	3/224/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	3/90/0
SD	Solderability, Pb	Steam age, 8 Hours	3/66/0	3/66/0
SD	Solderability, Pb-Free	Steam age, 8 Hours	3/66/0	3/66/0
MQ	Manufacturability	Per mfg. site specification	3/Pass	3/Pass
DS	Die Shear	Die	3/30/0	3/30/0
PD	Physical Dimensions	Per mechanical drawing	3/15/0	3/15/0
LFA	Lead Finish Adhesion	Leads, min. 3 units	3/45/0	3/45/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours

- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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